Samsung Galaxy S6 Teardown & Physical Analyses of Key Components - Reverse Technology Report

Description:
The Samsung Galaxy S6 holds many IC components which are listed and reviewed in the report. A special focus has been made to highlight the component structure and understand the manufacturing process on 11 "notable" components among 4 selected topics: Advanced packaging, MEMS/Sensor, RF and Imaging.

Five MEMS/Sensors components
- Fingerprint sensor – second generation
- eCompass - new reference which has never been used in a smartphone and smallest eCompass on the market
- OIS gyroscope – smallest gyroscope on the market
- Heart-rate monitor sensor and color, ambient light and proximity sensor - rarely integrated in a smartphone

Imaging components
- Front and rear camera modules as well as flash LED

Two packaging components
- Samsung Exynos Processor – advanced Package-on-Package (PoP) structure
- Samsung power management IC – smallest pitch Wafer-Level Package (WLP) on the board

One RF component
- Wi-Fi & Bluetooth combo module - flip-chip BGA SiP integrating the industry's most powerful 5G WiFi combo chip

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     - ICs Identification (mfr., ref., fcn., pkg. type, size & pin count)
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